

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of )  
Per LIGANDER et al. ) Group Art Unit: Unassigned  
Application No.: Unassigned ) Examiner: Unassigned  
Filed: August 30, 2001 )  
For: Sequentially Processed Circuitry )

#3/B  
18 Jan 02  
R. Talbot

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Before examination, please amend this application as follows

IN THE SPECIFICATION

Page 1, line 1, please ~~DELETE~~ "E42 P 39 US SBP";

line 2, please ~~DELETE~~ "2001-08-28";

line 7, please ~~REPLACE~~ the section heading with ~~-Background-~~; and

line 10, ~~DELETE~~ the section heading entirely.

Page 6, please ~~REPLACE~~ the paragraph beginning at line 14, with the following:

--Encapsulation of printed circuits, with or without active and/or passive circuitry, that are processed sequentially is necessary to prevent destruction of the circuit patterns, especially if they are made of environmentally sensitive materials and/or with very thin layers. There is a desire to reduce conductors of a circuit board to less than 5  $\mu\text{m}$  thick and less than 20  $\mu\text{m}$  wide. This has raised an interest in using less stable polymers such as acrylat as thin layers of dielectric. It has been proposed to use offset printing for manufacturing printed circuit boards and also for manufacture of active and passive components, such as transistor functions,

B<sup>2</sup>